

# Highly Versatile Buck-Boost Ambient Energy Manager with Source Voltage Level Configuration

## Feature

### Ultra-low power start-up

- Cold start from 275 mV input voltage and 3  $\mu$ W input power (typical).

### Constant input voltage regulation

- Optimized for intermittent and pulse power.
- Selectable operating input voltage from 140 mV to 4.5 V.

### Adaptive and smart energy management

- DCDC switches automatically between boost, buck-boost and buck operation, according to input and output voltages, to maximize energy transfer.
- DCDC automatically handles multiple inputs and outputs:
  - Keeps the internal supply and the load voltages regulated while storing the excess of energy in the storage element.
  - The storage element can be used as an input to keep the load and internal voltages regulated when no energy is available on the source.

### Load supply voltage

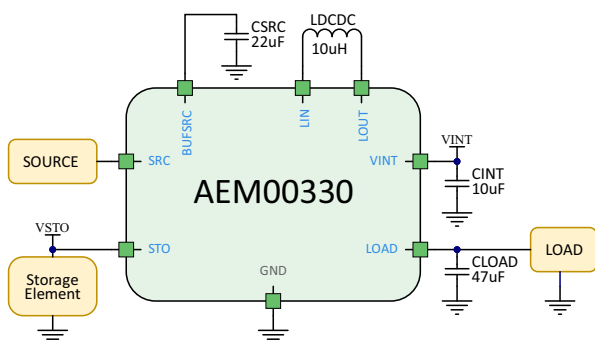
- Selectable load voltage from 1.2 V to 3.3 V.
- Current drive capability: 30 mA in low power mode, 60 mA in high power mode.

### Battery protection features

- Selectable over-charge and over-discharge protection for any type of rechargeable battery or (super-)capacitor.
- Fast super-capacitor charging.
- Dual cell super-capacitor balancing circuit.

### Smallest footprint, smallest BOM

- Only four external components are required.
- One 10  $\mu$ H inductor.
- Three capacitors: one 10  $\mu$ F, one 22  $\mu$ F and one at least 40  $\mu$ F.



## Description

The AEM00330 is an integrated energy management circuit that extracts DC power from an ambient energy harvesting source to simultaneously supply an application and store energy in a storage element. The AEM00330 allows to extend battery lifetime and ultimately eliminates the primary energy storage element in a large range of applications.

At start-up, user can choose between charging the storage element first to accumulate energy before the application circuit starts, or charge the load decoupling capacitor first to start the application circuit faster.

Thanks to its selectable operating input voltage, it is possible to set a voltage at which the AEM00330 operates. This voltage is between 140 mV and 4.5 V.

With its unique cold start circuit, the AEM00330 can start harvesting with an input voltage as low as 275 mV and from an input power of 3  $\mu$ W. The preset protection levels determine the storage element voltages protection thresholds to avoid over-charging and over-discharging the storage element and thus avoiding damaging it. Those are set through configuration pins. Moreover, custom threshold voltages can be obtained at the expense of a few configuration resistors.

The load voltage can be selected to cover most application needs, with a maximum available load current of 60 mA.

The chip integrates all active elements for powering a typical wireless sensor. Only three capacitors and one inductor are required.

## Applications

Door access systems      Smart wearable sensors  
Smart switches home/building      Point-of-sales (POS)

## Device Information

Part Number	Package	Body size [mm]
10AEM00330J0000	QFN 40-pin	5x5mm

## Evaluation Board

Part Number
2AAEM00330J001

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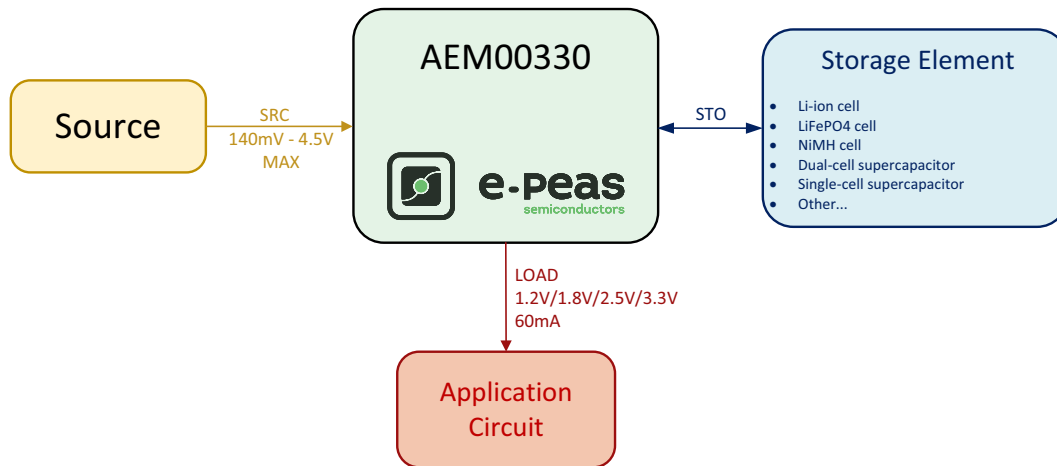
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## 1. Introduction

Figure 1: Simplified Schematic View

The AEM00330 is a full-featured energy efficient power management circuit able to harvest energy from an energy source (connected to **SRC**) to supply an application circuit (connected to **LOAD**) and use any excess of energy to charge a storage element (connected to **STO**). This is done with a minimal bill of material: only 3 capacitors and one inductor are needed for a basic setup.

The heart of the AEM00330 is a regulated switching DCDC converter with high power conversion efficiency.

At first start-up, as soon as a required cold-start voltage of 275 mV and a sparse amount of power of at least 3  $\mu$ W is available at the source, the AEM00330 coldstarts. After the cold start, the AEM extracts the power available from the source if the working input voltage is higher than  $V_{SRC,REG}$ .

Through four configuration pins (**STO\_CFG[3:0]**), the user can select a specific operating mode out of 15 modes that cover most application requirements without any dedicated external component. Those operating modes define the protection levels of the storage element. If none of those 15 modes fit the user's storage element, a custom mode is also available to allow the user to define a mode with custom specifications.

Status pins **ST\_STO**, **ST\_STO\_RDY** and **ST\_STO\_OVDIS** provide information about the voltage levels of the storage element. **ST\_STO** is HIGH when the voltage of the storage element  $V_{STO}$  is above  $V_{CHRDY}$  and is reset when the voltage drops below  $V_{OVDIS}$ . **ST\_STO\_RDY** is HIGH when  $V_{STO}$  is above  $V_{CHRDY}$ , and reset when  $V_{STO}$  drops below  $V_{CHRDY}$ . **ST\_STO\_OVDIS** is HIGH when  $V_{STO}$  drops below  $V_{OVDIS}$  and reset when  $V_{STO}$  is above  $V_{OVDIS}$ . Status pin **ST\_LOAD** is HIGH when the load voltage  $V_{LOAD}$  rises above  $V_{LOAD,TYP}$ , and is reset when  $V_{LOAD}$  drops below  $V_{LOAD,MIN}$ .

Depending on the harvester and the application, the source regulation voltage,  $V_{SRC,REG}$ , can be configured thanks to six configuration pins (**SRC\_LVL\_CFG[5:0]**).

Once started, if at any time the load requires more power than can be harvested from the energy source, the AEM00330 automatically uses the storage element to keep the load supplied.

The AEM00330's DCDC converter can work in two modes: **LOW POWER MODE** and **HIGH POWER MODE**, each one of these being optimized for a power range on **SRC** and **LOAD**.

The charging of the storage element can be prevented by pulling **EN\_STO\_CH** to GND, typically to protect the storage element if the temperature is too low/high to safely charge it.

The AEM00330 also implements a **SLEEP STATE**, which reduces the quiescent current to avoid wasting the energy stored on the storage element when **EN\_SLEEP** is HIGH.

At start-up, user can choose to prioritize starting the application circuit connected on **LOAD**, or charging the storage element connected on **STO**. This is set by the **STO\_PRIO** pin.

## 2. Pin Configuration and Functions

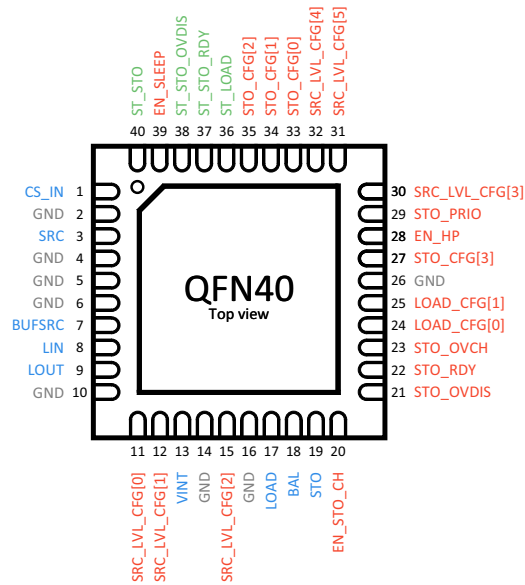


Figure 2: Pinout Diagram QFN 40-pin

NAME	PIN NUMBER	FUNCTION		
Power Pins				
CS_IN	1	Input for the eternal cold start circuit.		
SRC	3	Connection to the harvested energy source.		
BUFSRC	7	Connection to an external capacitor buffering the DCDC converter input.		
LIN	8	DCDC inductance connection.		
LOUT	9	DCDC inductance connection.		
VINT	13	Internal voltage supply.		
LOAD	17	Output voltage to supply on application load.		
BAL	18	Connection to mid-point of a dual-cell supercapacitor (optional). Must be connected to GND if not used.		
STO	19	Connection to the energy storage element - battery or (super-)capacitor. Cannot be left floating. Must be connected to a minimum capacitance of 100 μF or to a rechargeable battery.		
Status Pins				
ST_LOAD	36	Logic Output	HIGH: V_LOAD	HIGH when the LOAD voltage V_LOAD rises above the V_LOAD,TYP threshold. LOW when V_LOAD drops below V_LOAD,MIN threshold.
ST_STO_RDY	37	Logic Output	HIGH: V_LOAD	HIGH when V_STO is above V_CHRDY. LOW when V_STO drops below V_CHRDY.
ST_STO_OVDIS	38	Logic Output	HIGH: V_LOAD	HIGH when the AEM00330 state is SHUTDOWN STATE. LOW when in any other state.
ST_STO	40	Logic Output	HIGH: V_STO	HIGH when the storage device voltage V_STO rises above V_CHRDY threshold. LOW when V_STO drops below the V_OVDIS threshold.

Table 1: Power and Status Pins



NAME	PIN NUMBER	HIGH LEVEL	FLOATING STATE	FUNCTION
Configuration Pins				
SRC_LVL_CFG[0]	11	V <sub>VINT</sub>	HIGH	Used for the configuration of the source voltage level. Read as HIGH when left floating.
SRC_LVL_CFG[1]	12			
SRC_LVL_CFG[2]	15			
SRC_LVL_CFG[3]	30			
SRC_LVL_CFG[4]	32			
SRC_LVL_CFG[5]	31			
LOAD_CFG[0]	24	V <sub>VINT</sub>	HIGH	Used for the configuration of <b>LOAD</b> output voltage V <sub>LOAD</sub> . Read as HIGH when left floating.
LOAD_CFG[1]	25			
STO_CFG[0]	33	V <sub>VINT</sub>	HIGH	Used for the configuration of the threshold voltages for the energy storage element V <sub>OVDIS</sub> , V <sub>CHRDY</sub> and V <sub>OVCH</sub> . Read as HIGH when left floating.
STO_CFG[1]	34			
STO_CFG[2]	35			
STO_CFG[3]	27			
STO_PRIO	29	V <sub>VINT</sub>	HIGH	<ul style="list-style-type: none"><li>- Pulled up to <b>VINT</b> or floating: storage device (<b>STO</b>) has highest priority at start-up</li><li>- Pulled down to <b>GND</b>: load (<b>LOAD</b>) has highest priority at start-up</li></ul>
STO_OVCH	23	Used for the configuration of the threshold voltages (V <sub>OVDIS</sub> , V <sub>CHRDY</sub> and V <sub>OVCH</sub> ) for the energy storage element when <b>STO_CFG[3:0]</b> are set to custom mode (optional). Must be left floating if not used.		
STO_RDY	22			
STO_OVDIS	21			
EN_SLEEP	39	V <sub>LOAD</sub>	Cannot be left floating	<ul style="list-style-type: none"><li>- Pulled up to <b>LOAD</b>: <b>SLEEP STATE</b> enabled</li><li>- Pulled down to <b>GND</b>: <b>SLEEP STATE</b> disabled</li></ul>
EN_STO_CH	20	V <sub>LOAD</sub>	HIGH	<ul style="list-style-type: none"><li>- Pulled up to <b>LOAD</b> or floating: enables the charging of the battery</li><li>- Pulled down to <b>GND</b>: disables the charging of the battery</li></ul>
EN_HP	28	V <sub>VINT</sub>	HIGH	<ul style="list-style-type: none"><li>- Pulled up to <b>VINT</b> or floating: <b>HIGH POWER MODE</b> enabled</li><li>- Pulled down to <b>GND</b>: <b>HIGH POWER MODE</b> disabled</li></ul>
Other				
GND	2, 4, 5, 6, 10, 14, 16, 26	Ground connection, best possible connection to PCB ground plane.		
	Exposed pad			

Table 2: Configuration and Ground Pins

### 3. Absolute Maximum Ratings

Parameter	Value
Voltage on <b>LOAD</b> , <b>STO</b> , <b>SRC</b> , <b>BUFSRC</b> , <b>LIN</b> , <b>LOUT</b> , <b>BAL</b> , <b>CS_IN</b> , <b>EN_SLEEP</b> , <b>EN_STO_CH</b>	-0.3 V to 5.5 V
Voltage on <b>VINT</b> , <b>SRC_LVL_CFG[5:0]</b> , <b>LOAD_CFG[1:0]</b> , <b>STO_CFG[3:0]</b> , <b>STO_PRIO</b> , <b>STO_OVCH</b> , <b>STO_OVDIS</b> , <b>STO_RDY</b> , <b>EN_HP</b>	-0.3 V to 2.75 V
Operating junction temperature	-40 °C to 125 °C
Storage temperature	-65 °C to 150 °C
ESD HBM voltage	> 2000 V
ESD CDM voltage	> 500 V

Table 3: Absolute Maximum Ratings

### 4. Thermal Resistance

Package	$\theta_{JA}$	$\theta_{JC}$	Unit
QFN 40-pin	TBD	TBD	°C/W

Table 4: Thermal Resistance

#### ESD CAUTION



#### ESD (ELECTROSTATIC DISCHARGE) SENSITIVE DEVICE

These devices have limited built-in ESD protection and damage may thus occur on devices subjected to high-energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality





## 5. Typical Electrical Characteristics at 25 °C

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Power Conversion						
P <sub>SRC,CS</sub>	Source power required for cold start	V <sub>STO</sub> > V <sub>chrdy</sub>		3		μW
		V <sub>STO</sub> < V <sub>chrdy</sub>		6		μW
V <sub>SRC</sub>	Input voltage of the energy source	During cold start		0.275	4.5	V
		After cold start	0.14		4.5	V
V <sub>SRC,REG</sub> V <sub>SRC,REG</sub>	Regulation voltage of the source	See Table 10	Depends on SRC_LVL_CFG[5:0] configuration			V
Storage element						
V <sub>OVCH</sub>	Maximum voltage accepted on the storage element before disabling its charging	see Table 8	Depends on STO_CFG[3:0] configuration			V
V <sub>CHRDY</sub>	Minimum voltage required on the storage element before asserting the ST_STO					V
V <sub>OVDIS</sub>	Minimum voltage accepted on the storage element before entering into SHUTDOWN STATE					V
Load Output Voltage						
I <sub>LOAD,MAX</sub>	LOAD current drive capability	V <sub>LOAD</sub> = 1.8V V <sub>STO</sub> > 1.6V HP_EN = H		60		mA
		V <sub>LOAD</sub> = 2.5V V <sub>STO</sub> > 1.6V HP_EN = H		60		
		V <sub>LOAD</sub> = 3.3V V <sub>STO</sub> > 1.8V HP_EN = H		60		
V <sub>LOAD</sub>	Output voltage	see Table 9	Depends on LOAD_CFG[1:0] configuration			V
Internal supply & Quiescent Current						
V <sub>VINT</sub>	Internal voltage supply			2.2		V
I <sub>Q</sub>	Quiescent current on STO	V <sub>STO</sub> = 3.7V V <sub>LOAD</sub> = 2.5V EN_SLEEP = L EN_HP = L		875		nA
Symbol	Logic Level		LOW		HIGH	
Logic output pins						
ST_STO	Logic output levels on the status STO pin		GND		V <sub>STO</sub>	
ST_LOAD	Logic output levels on the status LOAD pin		GND		V <sub>LOAD</sub>	
ST_STO_RDY	Logic output levels on the status STO_READY pin		GND		V <sub>LOAD</sub>	
ST_STO_OVDIS	Logic output levels on the status STO_OVDIS pin		GND		V <sub>LOAD</sub>	

Table 5: Typical Electrical Characteristics

## 6. Recommended Operation Conditions

Symbol	Parameter	Min	Typ	Max	Unit
External Components					
L <sub>DCDC</sub>	Inductor of the DCDC converter		10		μH
C <sub>SRC</sub>	Capacitor decoupling the <b>SRC</b> terminal	13 <sup>1</sup>	22		μF
C <sub>INT</sub>	Capacitor decoupling the <b>VINT</b> terminal	5 <sup>1</sup>	10		μF
C <sub>LOAD</sub>	Capacitor decoupling the <b>LOAD</b> terminal	13 <sup>1</sup>	47		μF
C <sub>STO</sub>	Optional - Capacitor on <b>STO</b> if no storage element is connected (see Section 9.7.1)	100 <sup>1</sup>			μF
STO_OVCH	Configuration of V <sub>OVCH</sub> in custom mode	1	Section 9.4	100	MΩ
STO_OVDIS	Configuration of V <sub>OVDIS</sub> in custom mode				
STO_RDY	Configuration of V <sub>CHRDY</sub> in custom mode				
Symbol	Logic Level	LOW		HIGH	
Logic input pins					
LOAD_CFG[1:0]	Configuration pins for the <b>LOAD</b> voltage	GND		<b>VINT</b>	
SRC_LVL_CFG[5:0]	Configuration pins for the <b>SRC</b> voltage level	GND		<b>VINT</b>	
STO_CFG[3:0]	Configuration pins for the <b>STO</b> voltage	GND		<b>VINT</b>	
STO_PRIO	Configuration pin for the controller	GND		<b>VINT</b>	
EN_STO_FT	Configuration pin for the controller	GND		<b>VINT</b>	
EN_SLEEP	Configuration pin for the controller	GND		<b>LOAD</b>	
EN_STO_CH	Configuration pin for the controller	GND		<b>LOAD</b>	
EN_HP	Configuration pin for the controller	GND		<b>VINT</b>	

Table 6: Recommended Operation Conditions

1. Consider all component tolerance and deratings. Typically, DC-bias derating has a major impact on capacitance on ceramic capacitors.

## 7. Functional Block Diagram

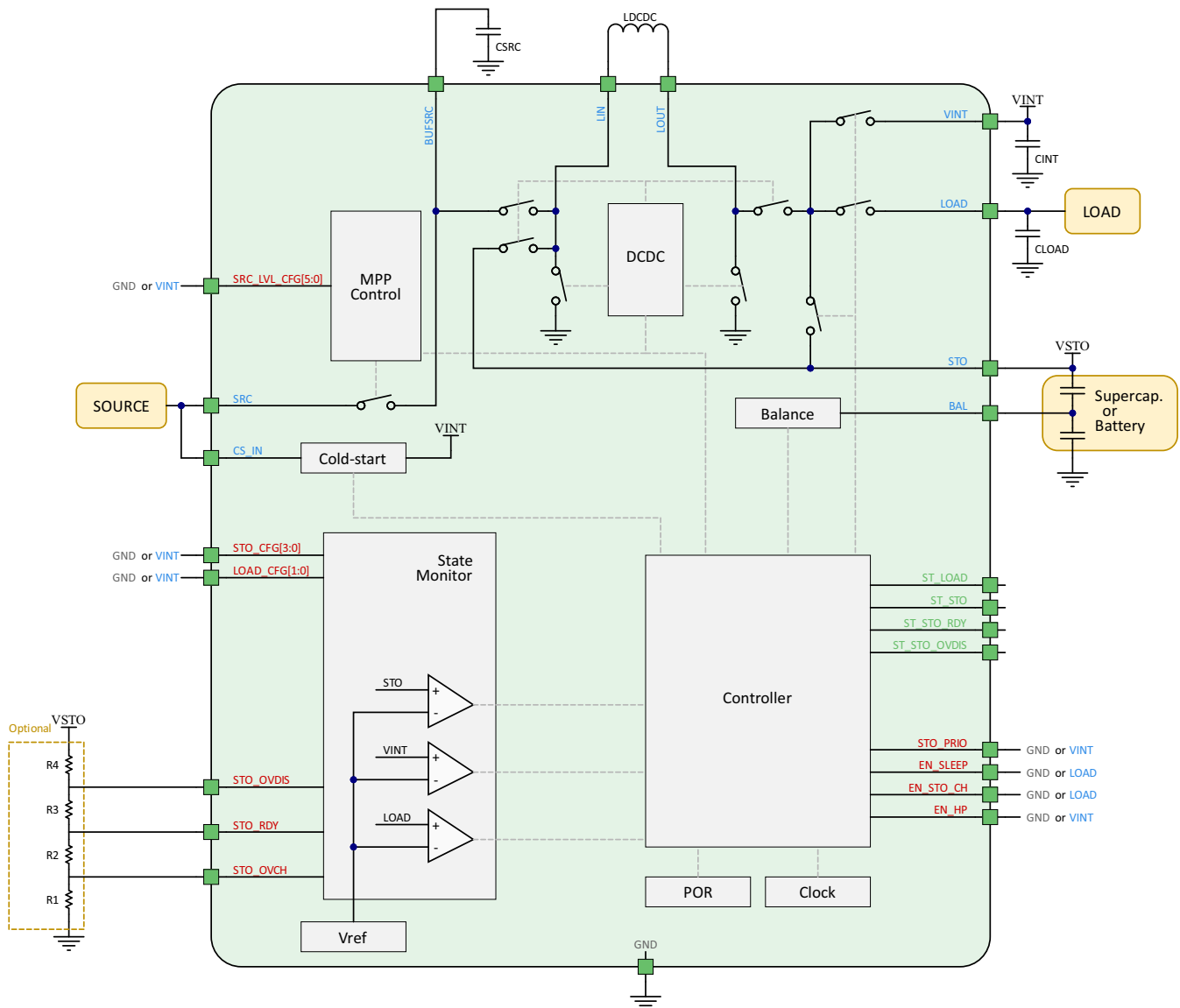


Figure 3: Functional Block Diagram

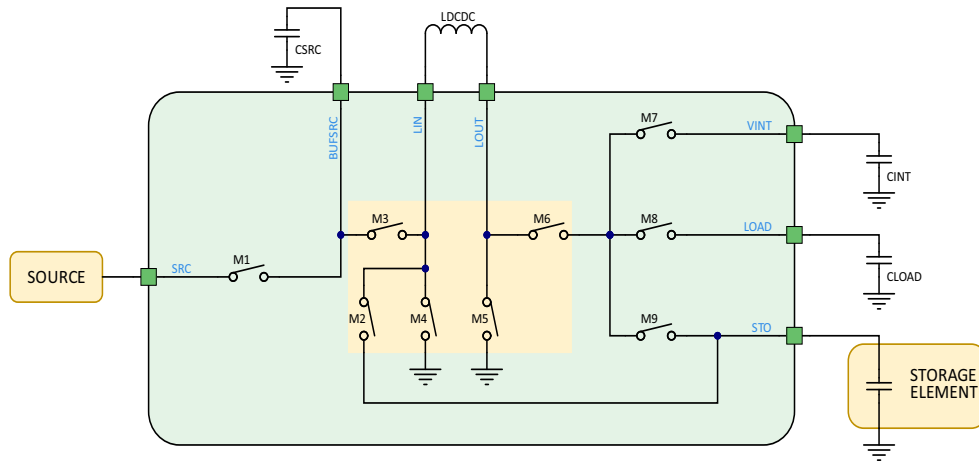


Figure 4: Simplified Schematic View of the AEM00330

## 8. Theory of Operation

### 8.1. DCDC Converter

The DCDC converter converts the voltage available at **BUFSRC** or at **STO** to a level suitable for charging the storage element **STO** or to regulate the **LOAD** and the internal supply **VINT**. The switching transistors of the DCDC converter are M2 or M3, M4, M5 and M6. Thanks to M7, M8 and M9, the controller selects between **LOAD**, **STO** and **VINT** respectively as the converter output. M1 selects the source as main input of energy. The internal supply **VINT** is regulated with priority over **LOAD**. **STO** is selected as an output only when neither **VINT** nor **LOAD** needs to be supplied. The converter has two possible inputs: **BUFSRC** or **STO**. **BUFSRC** is used by default as an input via M3. If the energy available on **SRC** is not sufficient to maintain the **LOAD** or **VINT** voltage, for instance because of a sudden current peak on **LOAD**, the converter uses **STO** instead as an input via M2 to keep **LOAD** and **VINT** regulated.

The reactive power component of this converter is the external inductor  $L_{DCDC}$ .  $V_{SRC}$  is regulated to  $V_{SRC,REG}$  configured by **SRC\_LVL\_CFG[5:0]**. **BUFSRC** is decoupled by the capacitor  $C_{SRC}$  which smooths the voltage against the current pulses pulled by the DCDC converter. The storage element is connected to the **STO** pin.

Depending on its input voltage and its output voltage, the DCDC converter will work as a boost converter, a buck converter or a buck-boost converter. The maximum power that can be harvested and supplied to the output **LOAD** depends on the power mode (**HIGH POWER MODE** or **LOW POWER MODE**), which is configured through the **EN\_HP** pin (see Section 9.1).

DCDC Converter Mode	Input Voltage / Output Voltage
Boost	$V_{IN} < V_{OUT} - 250 \text{ mV}$
Buck	$V_{IN} > V_{OUT} + 250 \text{ mV}$
Buck - Boost	$V_{OUT} - 250 \text{ mV} < V_{IN} < V_{OUT} + 250 \text{ mV}$

Table 7: DCDC Converter Modes

### 8.2. Cold-Start Circuit

The AEM00330 is able to coldstart if the voltage on **CS\_IN** is above 0.275 V. The minimum available power is:

- 3  $\mu\text{W}$  if  $V_{STO}$  is above  $V_{CHRDY}$ .
- 6  $\mu\text{W}$  if  $V_{STO}$  is below  $V_{CHRDY}$ .

**CS\_IN** is typically connected to **SRC** to allow the AEM00330 to coldstart from the energy available on the harvester. Nevertheless, any other energy source can be connected to **CS\_IN** as long as it meets the electrical specifications constraints described in Sections 5 and 6.

### 8.3. AEM00330 States Description

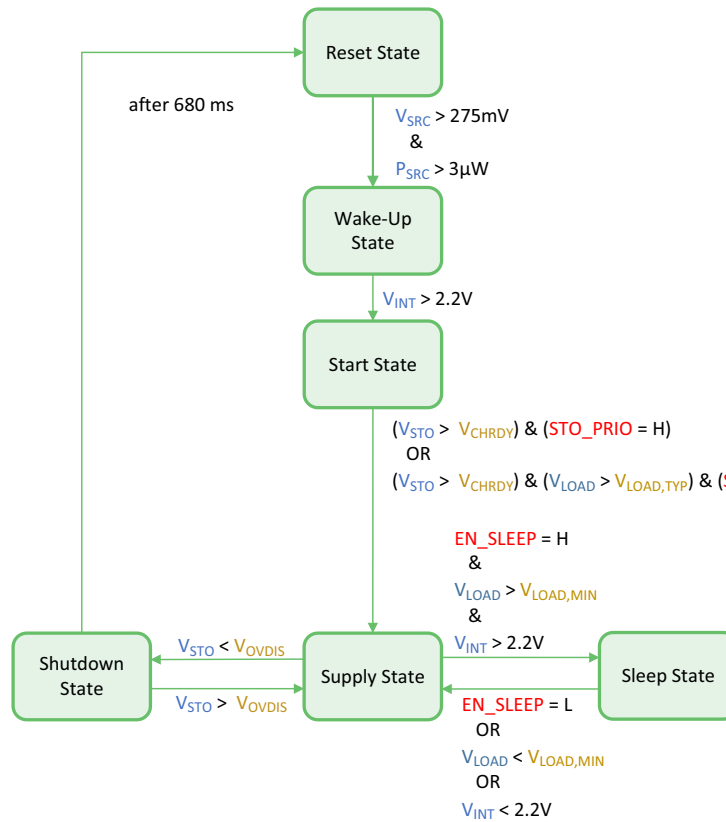


Figure 5: Diagram of the AEM00330 States

#### 8.3.1. Reset, Wake Up and Start States

The **RESET STATE** is a state where all nodes are deeply discharged and there is no available energy to be harvested. As soon as the required cold start voltage of 275 mV and a sparse amount of power of just 3  $\mu$ W become available on **CS\_IN** (usually connected to **SRC**), the AEM00330 switches to **WAKE-UP STATE**, and energy is extracted from **SRC** to make  $V_{INT}$  rise to 2.2 V. When  $V_{INT}$  reaches those 2.2 V, the AEM00330 switches to **START STATE**. In **START STATE**, two scenarios are possible: in the first scenario, **STO\_Prio** is HIGH, the storage element connected to **STO** has the priority on the one connected to **LOAD**. In the second scenario, **STO\_Prio** is reset and the **LOAD** has the priority.

When the AEM00330 is in **RESET STATE**, **WAKE-UP STATE** or **START STATE**, the DCDC converter's input is always **BUFSRC**: **STO** is never used as input. This guarantees that the storage element is not used until a minimum amount of energy has been stored in it.

#### 8.3.1.1. Storage Element Priority

This paragraph covers the AEM00330 behavior when **STO\_Prio** is pulled up to **VINT**, so that the storage element connected on **STO** has priority over **LOAD**.

##### Supercapacitor as a Storage Element

If the storage element is a supercapacitor, it may be fully discharged at first and thus need to be charged from 0 V. The DCDC converter charges **STO** from the input source (**SRC**). When  $V_{STO}$  reaches  $V_{CHRDY}$ , the circuit enters **SUPPLY STATE**.

##### Battery as a Storage Element

If the storage element is a battery, but its voltage is lower than  $V_{CHRDY}$ , then the storage element needs to be charged first until it reaches  $V_{CHRDY}$ . Once  $V_{STO}$  reaches  $V_{CHRDY}$ , or if the battery was initially charged above  $V_{CHRDY}$ , the circuit enters **SUPPLY STATE**.

### 8.3.1.2. Load Priority

If **STO\_Prio** is connected to GND, the AEM charges first the **LOAD** to  $V_{LOAD,MAX}$  (see Table 9) using energy from the source (**SRC**). This allows to first supply the application circuit connected to **LOAD**. If the storage element was initially charged above  $V_{CHRDY}$ , the circuit enters **SUPPLY STATE** as soon as **LOAD** reaches  $V_{LOAD,TYP}$ . If the storage element is a supercapacitor or a battery which voltage is lower than  $V_{CHRDY}$ , the AEM keeps regulating **LOAD** between  $V_{LOAD,MAX}$  and  $V_{LOAD,TYP}$ . Meanwhile, any excess charges on the source is used to charge the storage element until it reaches  $V_{CHRDY}$ . Once  $V_{STO}$  exceeds  $V_{CHRDY}$ , the circuit enters into **SUPPLY STATE**.

This configuration is useful when a large storage element is connected to **STO** and a smaller one is connected to **LOAD**: the application starts as soon as  $C_{LOAD}$  is charged and does not have to wait for the large storage element on **STO** to be charged.

### 8.3.2. Supply State

In **SUPPLY STATE**, four scenarios are possible:

- There is enough power provided by the source (**SRC**) to keep  $V_{LOAD}$  near  $V_{LOAD,TYP}$  with a small hysteresis and  $V_{VINT}$  at 2.2 V. The excessive power is used to charge the storage element on **STO**. In that case, the circuit remains in **SUPPLY STATE**. If **STO** is fully charged, **LOAD** will be maintained at  $V_{LOAD,MAX}$  instead of  $V_{LOAD,TYP}$ . If all nodes are fully charged, the DCDC converter is disabled to prevent over-charging the storage element, and the **SRC** pin is set to high impedance.
- If the circuit connected to **LOAD** consumes more energy than the energy that the AEM00330 is able to extract from the source, the **LOAD** circuit will be supplied by the storage element connected to the **STO** terminal. In this case, the circuit stays in **SUPPLY STATE**.
- Due to a lack of power from the source,  $V_{STO}$  falls below  $V_{OVDIS}$ . In this case, the circuit enters **SHUTDOWN STATE** as explained in Section 8.3.3.
- If **EN\_SLEEP** is HIGH and conditions (shown on Figure 5) on  $V_{LOAD}$  and  $V_{VINT}$  are satisfied, the AEM enters **SLEEP STATE** (see section 8.3.4).

### 8.3.3. Shutdown State

If the storage element gets depleted ( $V_{STO} < V_{OVDIS}$ ), the AEM00330 goes to **SHUTDOWN STATE**. As long as the AEM00330 is in this state, the **ST\_STO\_OVDIS** is HIGH. In **SHUTDOWN STATE**, if  $V_{STO}$  recovers within 680 ms, the AEM00330 goes back to **SUPPLY STATE**. This prevents false detection of the storage element being empty because of a **LOAD** current peak.

### 8.3.4. Sleep State

**SLEEP STATE** reduces the AEM00330 quiescent current by disabling the DCDC converter and by reducing the controller clock frequency. If  $V_{VINT}$  or  $V_{LOAD}$  fall below their regulation value, the AEM00330 temporarily exits **SLEEP STATE** to wake up the DCDC converter and supply **VINT** or **LOAD**. Exiting **SLEEP STATE** and waking up the DCDC converter takes up to 1 ms. Depending on the expected **LOAD** current,  $C_{LOAD}$  value must be adapted to act as an energy buffer during the 1 ms required to wake up the DCDC converter. Therefore, this state may be enabled when **LOAD** current is small, and be disabled if a high **LOAD** current is expected. As the DCDC is disabled, no energy is harvested from **SRC** while in **SLEEP STATE**, so that the storage element connected to **STO** is no longer charged. **LOAD** and **VINT** are the only nodes that are still supplied and regulated when the AEM00330 is in **SLEEP STATE**. This mode is useful to limit the current drawn on **STO** when the application circuit has detected that the power available on **SRC** is so low that it wouldn't compensate the AEM00330 internal circuit power consumption (see Table 5).

The AEM00330 enters **SLEEP STATE** if all the following conditions are satisfied:

- **EN\_SLEEP** pin pulled up to **LOAD** (H)
- $V_{VINT} > 2.2 \text{ V}$
- $V_{LOAD} > V_{LOAD,TYP}$

The AEM00330 leaves **SLEEP STATE** and switches back to **SUPPLY STATE** if one of the following conditions is satisfied:

- **EN\_SLEEP** pin pulled down to GND (L)
- $V_{VINT} < 2.2 \text{ V}$
- $V_{LOAD} < V_{LOAD,TYP}$

The AEM00330 will then stay in **SUPPLY STATE** until the **SLEEP STATE** conditions are all satisfied again.

## 8.4. Source Voltage Regulation

During **SUPPLY STATE**, the voltage on **SRC** is regulated to a voltage configured by the user. The AEM00330 offers a choice of fifty-nine values for the source voltage. If the open-circuit voltage of the harvester is lower than  $V_{SRC,REG}$ , the AEM00330 does not extract the power from the source. If the **SRC** voltage is higher, the AEM00330 regulates  $V_{SRC}$  to  $V_{SRC,REG}$  and extracts power.

## 8.5. Balancing for Dual-Cell Supercapacitor

The balancing circuit allows the user to balance the internal voltage of the dual-cell supercapacitor connected to **STO** in order to avoid damaging the supercapacitor because of excessive voltage on one cell.

If **BAL** is connected to **GND**, the balancing circuit is disabled. This configuration must be used if a battery, a capacitor or a single-cell supercapacitor is connected on **STO**.

If **BAL** is connected to the node between both cells of a supercapacitor, the balancing circuit compensates for any mismatch of the two cells that could lead to the over-charge of one of two cells. The balancing circuit ensures that **BAL** remains close to  $V_{STO} / 2$ . This configuration must be used if a dual-cell supercapacitor is connected to **STO**, and that this supercapacitor requires cells balancing.

The balancing circuit works as follows, with  $V_{BAL}$  the voltage on the **BAL** pin:

- $V_{BAL} > \frac{V_{STO}}{2}$ : the AEM00330 enables a switch between **BAL** and **GND** to discharge the bottom supercapacitor cell to **GND** (up to 20 mA).
- $V_{BAL} < \frac{V_{STO}}{2}$ : the AEM00330 enables a switch between **STO** and **BAL** to discharge the top supercapacitor cell to the bottom supercapacitor cell (up to 20 mA).

*NOTE: the balancing feature is optimized for supercapacitors, for use with other storage elements (batteries, etc.), please contact e-peas support.*

## 9. System Configuration

### 9.1. High Power / Low Power Mode

When **EN\_HP** is pulled to **VINT**, the DCDC converter is configured to **HIGH POWER MODE**. This allows higher currents to be extracted from the DCDC converter input (**SRC** or **STO**) to the DCDC converter output (**LOAD** or **STO**). Figure 6 shows the maximum current that the DCDC converter can supply to **LOAD**, depending on the storage voltage  $V_{STO}$ , for every available load voltage  $V_{LOAD}$ , for both **HIGH POWER MODE** and **LOW POWER MODE**.

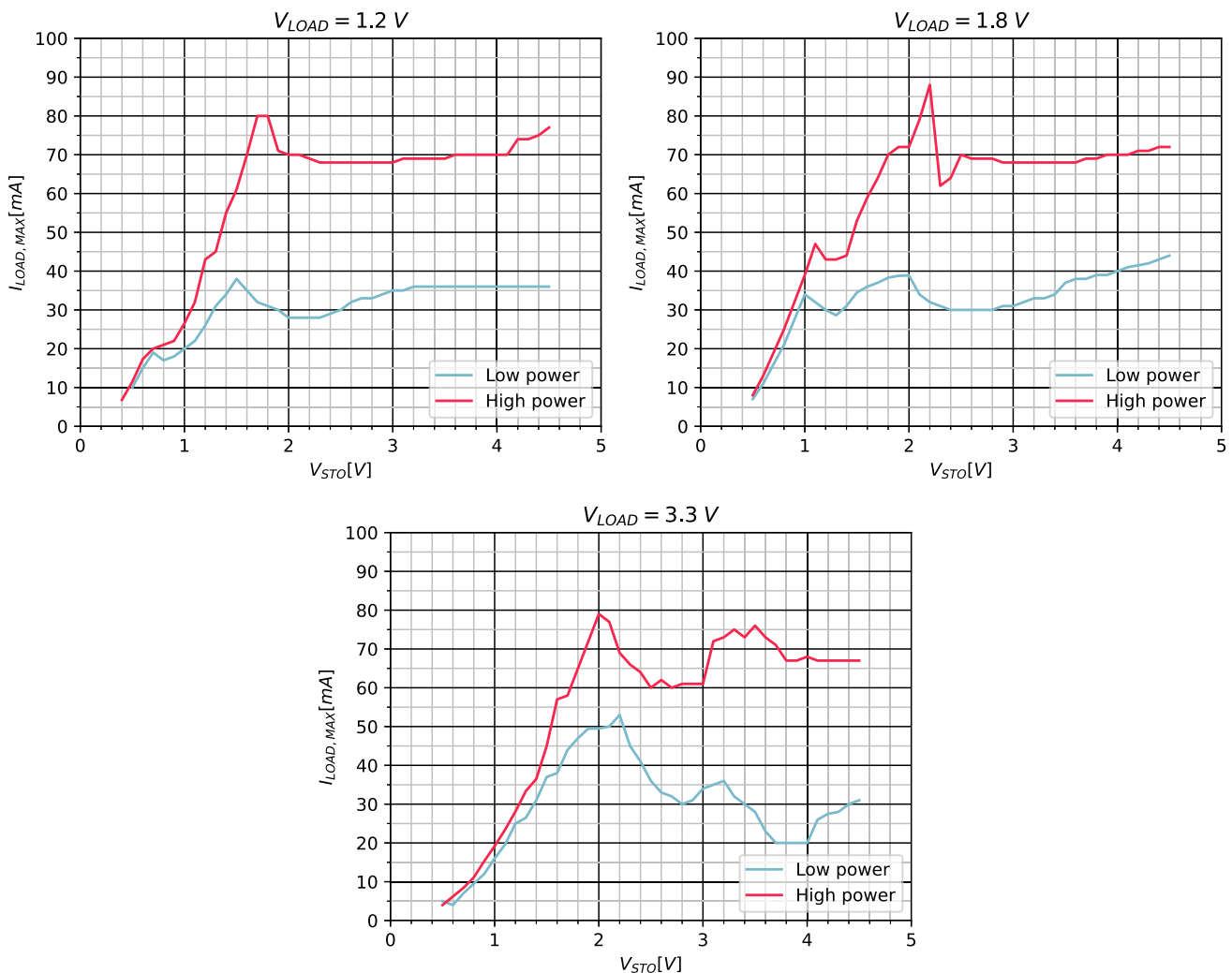


Figure 6: Maximum LOAD Current Depending on  $V_{STO}$  and on  $V_{LOAD}$

### 9.2. Storage Element Configuration

Through four configuration pins (**STO\_CFG[3:0]**), the user can set a particular operating mode from a range that covers most application requirements, without any dedicated external component as shown in Table 8. The three threshold levels are defined as:

- **$V_{OVCH}$** : maximum voltage accepted on the storage element before disabling its charging.
- **$V_{CHRDY}$** : minimum voltage required on the storage element before starting to supply the **LOAD** (if **STO\_Prio** is HIGH) and entering supply state after start-up.



- $V_{OVDIS}$ : minimum voltage accepted on the storage element before considering the storage element as depleted, thus setting  $ST\_STO$  LOW.

A large-size storage element is not mandatory on  $STO$ :

- If the harvested energy source is permanently available and covers the application needs or

- If the application does not need to store energy when the harvested energy source is not available

The storage element may then be replaced by an external capacitor  $C_{STO}$  with a minimum value of 100  $\mu F$ .

**CAUTION: running the AEM00330 without this 100  $\mu F$  minimum capacitance on  $STO$  will permanently damage the circuit.**

Configuration pins				Storage element threshold voltages			Typical use
$STO\_CFG[3:0]$				$V_{OVDIS}$	$V_{CHRDY}$	$V_{OVCH}$	
L	L	L	L	3.00 V	3.50 V	4.05 V	LiCoO <sub>2</sub> battery, Li-Po battery, Lithium Titanate (3.8 V) battery (long life).
L	L	L	H	2.80 V	3.10 V	3.60 V	LiFePO <sub>4</sub> battery, Lithium capacitor (LiC).
L	L	H	L	1.85 V	2.40 V	2.70 V	Dual-cell NiMH battery, Lithium-Titanate (2.4V) battery.
L	L	H	H	0.20 V	1.00 V	4.65 V	Dual-cell supercapacitor.
L	H	L	L	0.20 V	1.00 V	2.60 V	Single-cell supercapacitor.
L	H	L	H	1.00 V	1.20 V	2.95 V	Single-cell supercapacitor.
L	H	H	L	1.85 V	2.30 V	2.60 V	Lithium-Titanate battery (2.4V).
L	H	H	H	Custom Mode (single-cell NiMH battery, LiC, etc.) <sup>1</sup> .			
H	L	L	L	1.10 V	1.25 V	1.50 V	Ni-Cd single-cell battery.
H	L	L	H	2.20 V	2.50 V	3.00 V	Ni-Cd dual-cell battery.
H	L	H	L	1.45 V	2.00 V	4.65 V	Dual-cell supercapacitor.
H	L	H	H	1.00 V	1.20 V	2.60 V	Single-cell supercapacitor.
H	H	L	L	2.00 V	2.30 V	2.60 V	Solid State battery.
H	H	L	H	3.00 V	3.50 V	4.35 V	LiCoO <sub>2</sub> battery, Li-Po battery, Lithium Titanate (3.8 V) battery.
H	H	H	L	2.60 V	2.70 V	4.00 V	Tadiran TLI.
H	H	H	H	2.60 V	3.50 V	3.90 V	Tadiran HLC.

Table 8: Storage Element Configuration Pins

1. An example of a single-cell NiMH batteries optimized custom mode setting can be found at Section 10.2.

### 9.3. Load Configuration

The **LOAD** output voltage  $V_{LOAD}$  can be configured thanks to the **LOAD\_CFG[1:0]** configuration pins covering most application cases (see Table 9).  $V_{LOAD}$  is regulated to  $V_{LOAD,TYP}$ . However, if  $V_{LOAD}$  falls below  $V_{LOAD,MID}$ , the controller forces **STO** as an input of the DCDC converter to supply **LOAD**.

When the AEM00330 is in **SUPPLY STATE**:

- $V_{LOAD} < V_{LOAD,MID}$ : the AEM00330 charges  $C_{LOAD}$  by transferring the energy available on the storage element **STO** (if  $V_{STO}$  is above  $V_{OVDIS}$ ), even if energy is available on **SRC**.
- $V_{LOAD,MID} < V_{LOAD} < V_{LOAD,MAX}$ :
  - If energy is available on **SRC**, the AEM00330 uses it to charge  $C_{LOAD}$ .
  - If no energy is available on **SRC**, the AEM00330 uses the energy available on **STO** to charge  $C_{LOAD}$ .

- $V_{LOAD,TYP}$  is the typical average voltage to be expected on the **LOAD** pin.
- **ST\_LOAD** reflects  $V_{LOAD}$ , with an hysteresis between  $V_{LOAD,MIN}$  and  $V_{LOAD,TYP}$ :
  - **ST\_LOAD** is HIGH when  $V_{LOAD} > V_{LOAD,TYP}$ .
  - **ST\_LOAD** is LOW when  $V_{LOAD} < V_{LOAD,MIN}$ .
- As a reminder, the order of priority in which the nodes are recharged is as follows:
  - **VINT** always has the highest priority, as it is mandatory to keep the AEM00330 internal circuit supplied.
  - **LOAD** has the second highest priority, to keep the application circuit supplied.
  - **STO** has the lowest priority, as the storage element is used to store the excessive energy from **SRC**.

Configuration pins		LOAD output voltage			
<b>LOAD_CFG[1:0]</b>		$V_{LOAD,MIN}$	$V_{LOAD,MID}$	$V_{LOAD,TYP}$	$V_{LOAD,MAX}$
L	L	3.15 V	3.23 V	3.28 V	3.34 V
L	H	2.35 V	2.47 V	2.50 V	2.53 V
H	L	1.64 V	1.75 V	1.79 V	1.82 V
H	H	1.14 V	1.16 V	1.20 V	1.23 V

Table 9: Load Configuration Pins

### 9.4. Custom Mode Configuration

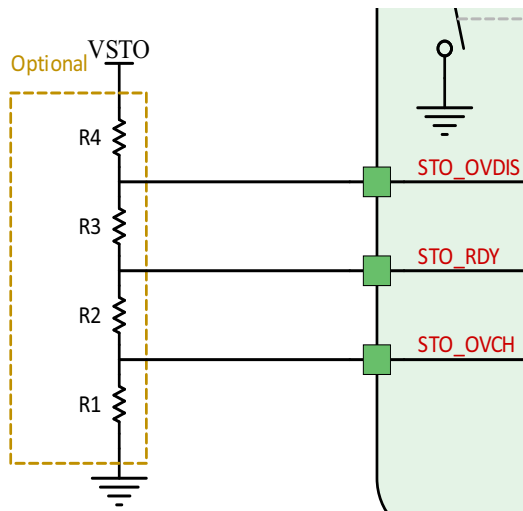


Figure 7: Custom Mode Settings

When **STO\_CFG[3:0] = LHHH**, the custom mode is selected and all four configuration resistors must be wired as shown in Figure 7.

$V_{OVCH}$ ,  $V_{CHRDY}$  and  $V_{OVDIS}$  are defined thanks to  $R_1$ ,  $R_2$ ,  $R_3$  and  $R_4$ , which can be determined within the following constraints:

- $R_T = R_1 + R_2 + R_3 + R_4$
- $1M\Omega \leq R_T \leq 100M\Omega$
- $R_1 = R_T \cdot \frac{1V}{V_{OVCH}}$
- $R_2 = R_T \cdot \left( \frac{1V}{V_{CHRDY}} - \frac{1V}{V_{OVCH}} \right)$
- $R_3 = R_T \cdot \left( \frac{1V}{V_{OVDIS}} - \frac{1V}{V_{CHRDY}} \right)$
- $R_4 = R_T \cdot \left( 1 - \frac{1V}{V_{OVDIS}} \right)$

The resistors should have high values to make the additional power consumption negligible. Moreover, the following constraints must be respected to ensure the functionality of the chip:

- $V_{CHRDY} + 0.05V \leq V_{OVCH} \leq 4.5V$
- $V_{OVDIS} + 0.05V \leq V_{CHRDY} \leq V_{OVCH} - 0.05V$
- $1V \leq V_{OVDIS}$



## 9.5. Disable Storage Element Charging

Pulling down **EN\_STO\_CH** pin to **GND** disables the charging of the storage element connected to **STO** from **SRC**. This can be done for example to protect the storage element when the system detects that the environment temperature is too low or too high to safely charge the storage element.

While **EN\_STO\_CH** is pulled down, **VINT** and **LOAD** can still be supplied either from **SRC** or from **STO**.

To enable charging the storage element on **STO**, **EN\_STO\_CH** must be pulled up to **LOAD** or left floating (pin is pulled up internally).

Please note that **STO** will still be charged to **V<sub>CHRDY</sub>** during the **START STATE**



## 9.6. Source Level Configuration

Six dedicated configuration pins, **SRC\_LVL\_CFG[5:0]**, allow selecting the  $V_{\text{SRC,REG}}$  at which the source regulates its voltage.

Configuration pins						Voltage Level
<b>SRC_LVL_CFG[5:0]</b>						$V_{\text{SRC,REG}}$
L	L	L	L	L	L	0.14 V
L	L	L	L	L	H	0.17 V
L	L	L	L	H	L	0.20 V
L	L	L	L	H	H	0.23 V
L	L	L	H	L	L	0.26 V
L	L	L	H	L	H	0.30 V
L	L	L	H	H	L	0.34 V
L	L	L	H	H	H	0.39 V
L	L	H	L	L	L	0.43 V
L	L	H	L	L	H	0.48 V
L	L	H	L	H	L	0.52 V
L	L	H	L	H	H	0.57 V
L	L	H	H	L	L	0.61 V
L	L	H	H	L	H	0.66 V
L	L	H	H	H	L	0.70 V
L	L	H	H	H	H	0.75 V
L	H	L	L	L	L	0.80 V
L	H	L	L	L	H	0.84 V
L	H	L	L	H	L	0.89 V
L	H	L	L	H	H	0.95 V
L	H	L	H	L	L	1.05 V
L	H	L	H	L	H	1.14 V
L	H	L	H	H	L	1.23 V
L	H	L	H	H	H	1.32 V
L	H	H	L	L	L	1.41 V
L	H	H	L	L	H	1.50 V
L	H	H	L	H	L	1.59 V
L	H	H	L	H	H	1.68 V
L	H	H	H	L	L	1.77 V
L	H	H	H	L	H	1.86 V

Configuration pins						Voltage Level
<b>SRC_LVL_CFG[5:0]</b>						$V_{\text{SRC,REG}}$
L	H	H	H	H	L	1.95 V
L	H	H	H	H	H	2.05 V
H	L	L	L	L	L	2.14 V
H	L	L	L	L	H	2.23 V
H	L	L	L	H	L	2.32 V
H	L	L	L	H	H	2.41 V
H	L	L	H	L	L	2.50 V
H	L	L	H	L	H	2.59 V
H	L	L	H	H	L	2.68 V
H	L	L	H	H	H	2.77 V
H	L	H	L	L	L	2.86 V
H	L	H	L	L	H	2.95 V
H	L	H	L	H	L	3.05 V
H	L	H	L	H	H	3.14 V
H	L	H	H	L	L	3.23 V
H	L	H	H	L	H	3.32 V
H	L	H	H	H	L	3.41 V
H	L	H	H	H	H	3.50 V
H	H	L	L	L	L	3.59 V
H	H	L	L	L	H	3.68 V
H	H	L	L	H	L	3.77 V
H	H	L	L	H	H	3.86 V
H	H	L	H	L	L	3.95 V
H	H	L	H	L	H	4.05 V
H	H	L	H	H	L	4.14 V
H	H	L	H	H	H	4.23 V
H	H	H	L	L	L	4.32 V
H	H	H	L	L	H	4.41 V
H	H	H	L	H	L	4.50 V

Table 10: Source regulation configuration pins

## 9.7. External Components

Refer to Figure 17 to have an illustration of the external components wiring.

### 9.7.1. Storage Element Information

The energy storage element of the AEM00330 can be a rechargeable battery, a supercapacitor or a capacitor. The size of the storage element must be determined so that its voltage does not fall below  $V_{OVDIS}$  even during current peaks pulled by the application circuit connected to **LOAD**. If the internal resistance of the storage element cannot sustain this voltage limit, it is advisable to decouple the battery with a capacitor.

If the application expects a disconnection of the battery (e.g. because of a user removable connector), the PCB should include a capacitor  $C_{STO}$  of at least 100  $\mu F$  connected between **STO** and **GND**. The leakage current of the storage element should be small as leakage currents directly impact the quiescent current of the whole subsystem.

### 9.7.2. External Inductor Information

The AEM00330 operates with one standard miniature inductor.  $L_{DCDC}$  must sustain a peak current of at least 1 A and a switching frequency of at least 10 MHz. Low equivalent series resistance (ESR) favors the power conversion efficiency of the DCDC converter. The recommended value is 10  $\mu H$ .

### 9.7.3. External Capacitors Information

#### 9.7.3.1. $C_{SRC}$

This capacitor acts as an energy buffer at the input of the DCDC converter. It prevents large voltage fluctuations when the DCDC converter is switching. The recommended nominal value is 22  $\mu F$ .

#### 9.7.3.2. $C_{INT}$

This capacitor acts as an energy buffer for the internal voltage supply. The recommended nominal value is 10  $\mu F$ .

#### 9.7.3.3. $C_{LOAD}$

This capacitor acts as an energy buffer for **LOAD**. It also reduces the voltage ripple induced by the current pulses inherent to the switched behavior of the converter. The recommended value is at least 13  $\mu F$  (considering derating and tolerance).

## 10. Typical Application Circuits

### 10.1. Example Circuit 1

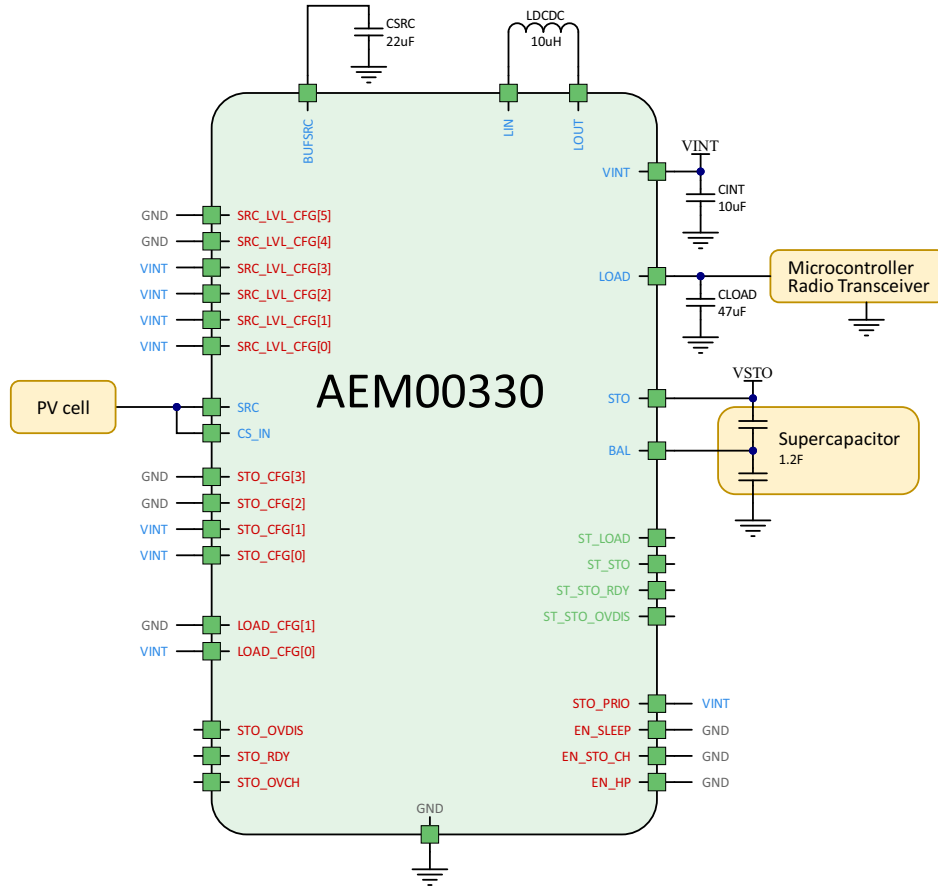


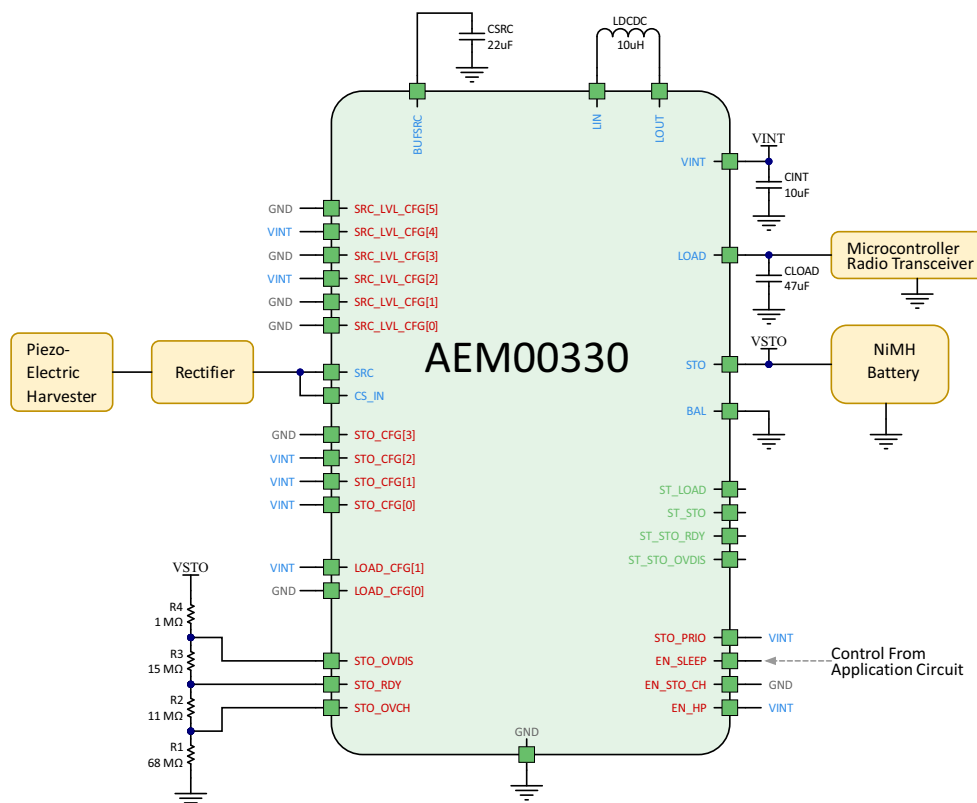
Figure 8: Typical Application Circuit 1

The circuit is an example of a system with solar energy harvesting. It uses a pre-defined operating mode that uses standard components, and a supercapacitor as energy storage.

- Energy source: PV cell.
- **SRC\_LVL\_CFG[5:0] = LLHHHH**: the AEM00330 starts to extract power from 0.75 V and regulates  $V_{SRC}$  to 0.75 V.
- **STO\_CFG[3:0] = LLHH**: the storage element is a dual-cell supercapacitor, with:
  - $V_{OVCH} = 4.65$  V
  - $V_{CHRDY} = 1.00$  V
  - $V_{OVDIS} = 0.20$  V

- The balancing pin of the dual-cell supercapacitor is connected to **BAL**.
- **LOAD\_CFG[1:0] = LH**: the microcontroller and the radio transceiver are supplied by the **LOAD** terminal, which is regulated at  $V_{LOAD} = 2.50$  V.
- **STO\_Prio** is connected to **VINT**: at start-up **STO** will be charged and before **LOAD**.
- **EN\_SLEEP** is connected to **GND**: the AEM00330 will never switch to **SLEEP STATE**.
- **EN\_STO\_CH** is connected to **VINT**: the charging of the storage element on **STO** is enabled.
- **EN\_HP** is connected to **GND**: the DCDC converter is in **LOW POWER MODE**.

## 10.2. Example Circuit 2



*Figure 9: Typical Application Circuit 2*

The circuit is an example of a system with vibration energy harvesting. It uses a rechargeable NiMH battery as storage element. The voltage thresholds are set by the custom mode.

- Energy source: piezoelectric vibration harvester.
- **SRC\_LVL\_CFG[5:0]** = LHLHLL: the AEM00330 starts to extract power from 1.05 V and regulates  $V_{SRC}$  to 1.05 V.
- **STO\_CFG[3:0]** = LHHH: the storage element is a NiMH rechargeable battery, used with custom mode:
  - $V_{OVDIS} = 1.00\text{ V}$
  - $V_{CHRDY} = 1.20\text{ V}$
  - $V_{OVCH} = 1.40\text{ V}$
- Custom mode resistor divider calculations (values have been chosen to match E24 series value):
  - $R_T = 95\text{ M}\Omega$
  - $R_1 = R_T \cdot \frac{1\text{ V}}{V_{OVCH}} \approx 68\text{ M}\Omega$
  - $R_2 = R_T \cdot \left( \frac{1\text{ V}}{V_{CHRDY}} - \frac{1\text{ V}}{V_{OVCH}} \right) \approx 11\text{ M}\Omega$
  - $R_3 = R_T \cdot \left( \frac{1\text{ V}}{V_{OVDIS}} - \frac{1\text{ V}}{V_{CHRDY}} \right) \approx 15\text{ M}\Omega$

$$- R_4 = R_T \cdot \left(1 - \frac{1V}{V_{OVPD5}}\right) \approx 1M\Omega$$

- **BAL** is not used (not a dual-cell storage element) so it is connected to **GND**.
- **LOAD\_CFG[1:0]** = **HL**: the micro-controller and the radio transceiver are supplied by the **LOAD** terminal, which is regulated at  $V_{LOAD} = 1.79\text{ V}$ .
- **STO\_PRI0** is connected to **VINT**: at start-up **STO** will be charged and before **LOAD**.
- **EN\_SLEEP** is controlled by the application circuit, typically by a microcontroller GPIO output.
- **EN\_STO\_CH** is connected to **LOAD**: the charging of the storage element present on **STO** is enabled.
- **EN\_HP** is connected to **VINT**: the DCDC converter is in **HIGH POWER MODE**.

*NOTE: for LiC (Lithium-ion Capacitor) storage elements, or others that would not be covered by **STO\_CFG[3:0]** presets, please apply the same equations as in the above example to determine custom mode resistors values. E24 series values for typical storage elements can be found in the AEM00330 Configuration Tool spreadsheet, to be downloaded on e-peas website.*

## 11. Circuit Behavior

### 11.1. Wake-up state, Start state and Supply state

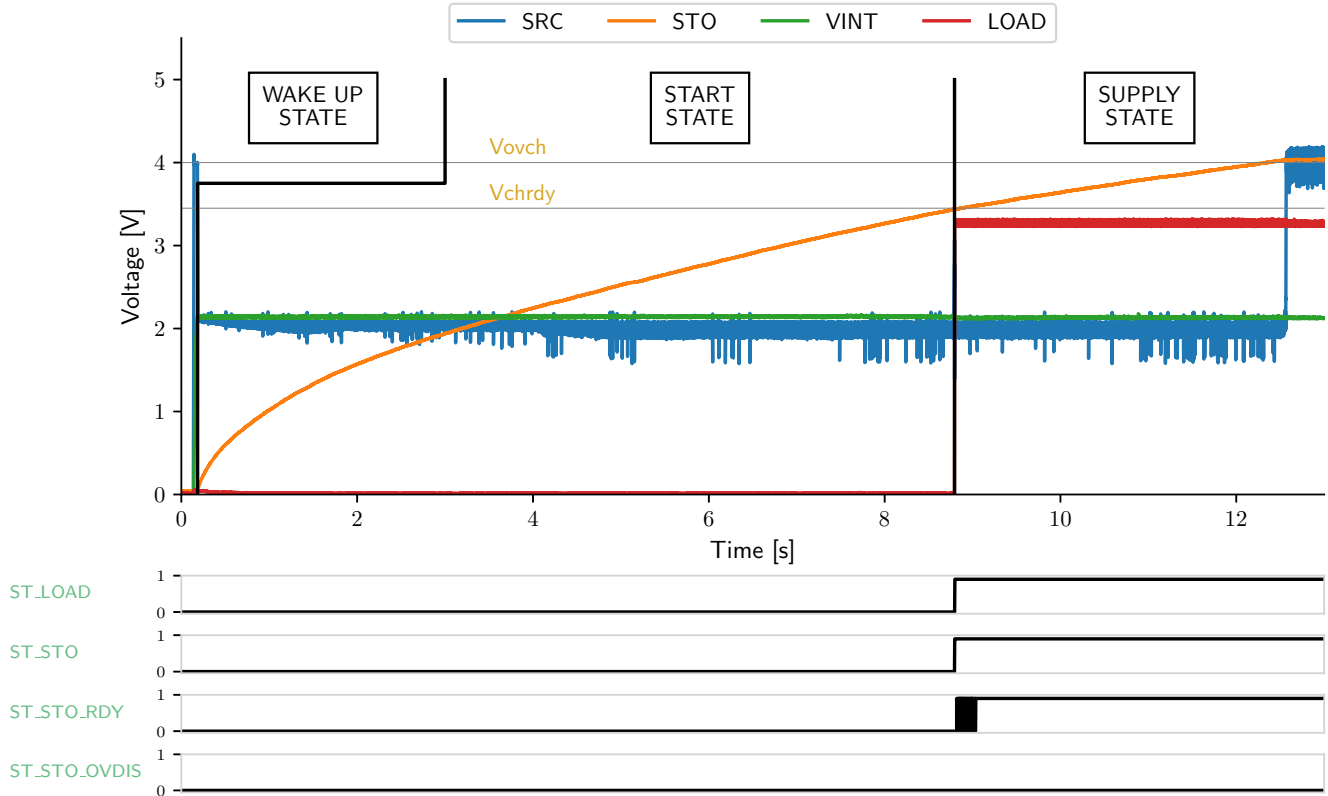


Figure 10: Wake-up state, Start state and Supply state

- **STO\_CFG[3:0]** = LLLL
- **V\_OVDIS** = 3.00 V
- **V\_CHRDY** = 3.50 V
- **V\_OVCH** = 4.05 V
- **SRC\_LVL\_CFG[5:0]** = LHHHHH ( $V_{SRC,REG} = 2.05$  V)
- **C\_STO** = 10 mF
- **SRC**: 5 mA current source with 4 V voltage compliance
- **LOAD\_CFG[1:0]** = LL ( $V_{LOAD,TYP} = 3.28$  V)
- **EN\_HP** = H (high power mode)
- **EN\_STO\_CH** = H (storage element charge enabled)
- **STO\_Prio** = H (storage element charged in priority after startup)
- **EN\_SLEEP** = L (sleep mode disabled)



## 11.2. Supply state, Shutdown state and Reset state

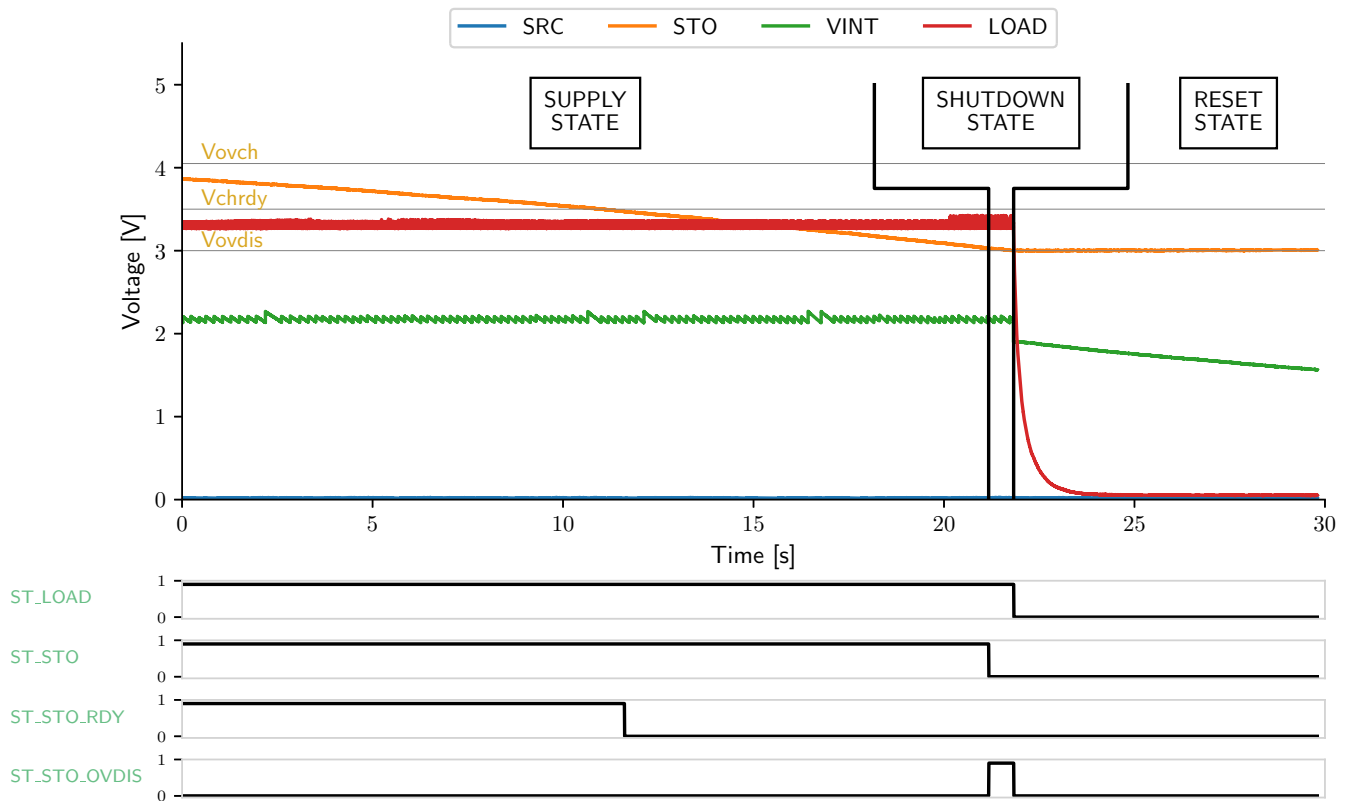


Figure 11: Supply State, Shutdown state and Reset state

- **STO\_CFG[3:0]** = LLLL
  - $V_{OVDIS} = 3.00\text{ V}$
  - $V_{CHRDY} = 3.50\text{ V}$
  - $V_{OVCH} = 4.05\text{ V}$
- **LOAD\_CFG[1:0]** = LL ( $V_{LOAD,TYP} = 3.28\text{ V}$ )
- **SRC\_LVL\_CFG[5:0]** = LHHHHH ( $V_{SRC,REG} = 2.05\text{ V}$ )
- $C_{STO} = 10\text{ mF}$
- **SRC**: left floating force the storage element on **STO** to discharge
- **EN\_HP** = H (high power mode)
- **STO\_Prio** = H (storage element charged in priority after startup)
- **EN\_STO\_CH** = H (storage element charge enabled)
- **EN\_SLEEP** = L (sleep mode disabled)
- 10 kΩ connected between **LOAD** and GND

## 12. Performance Data

### 12.1. DCDC Conversion Efficiency From SRC to STO in Low Power Mode

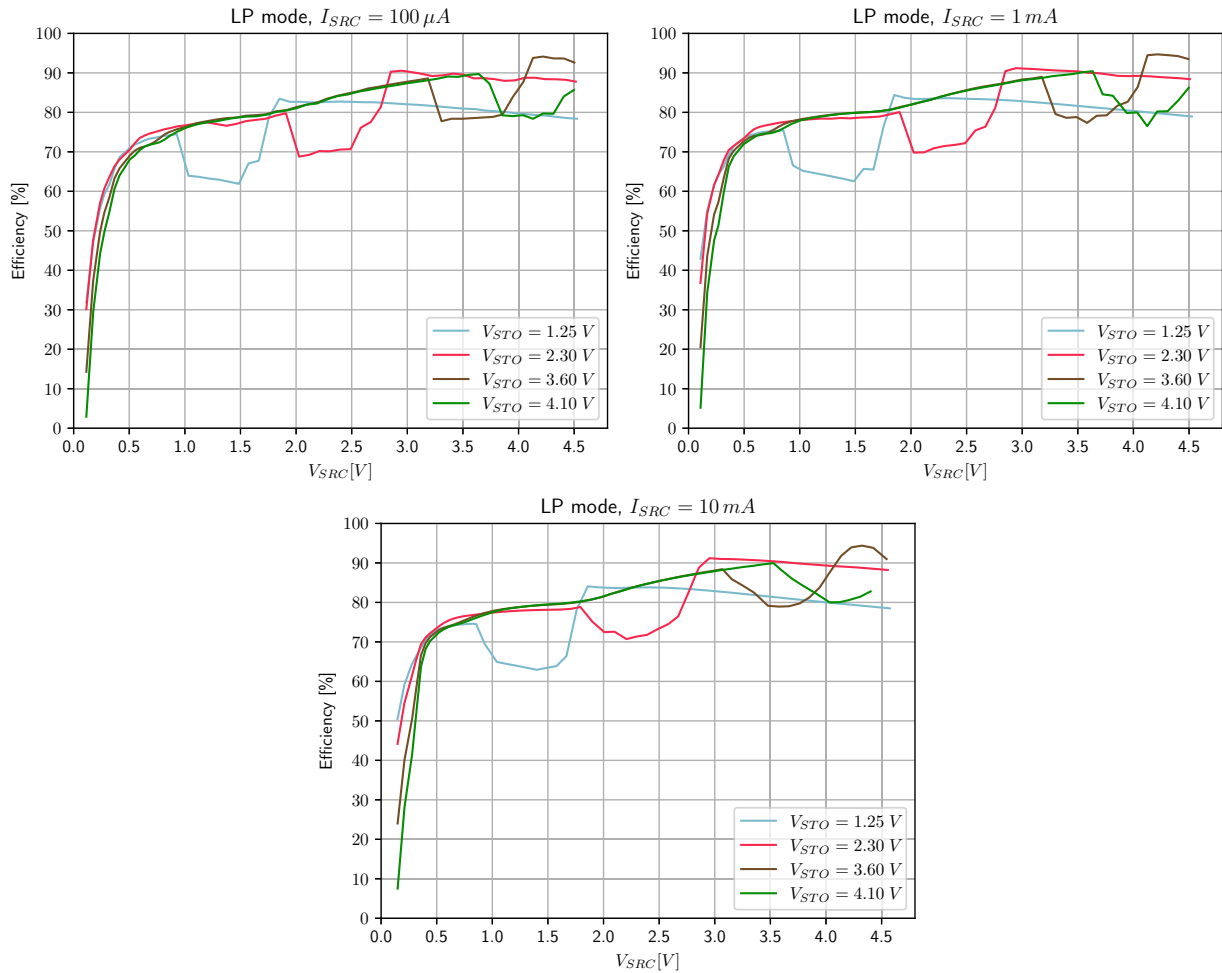


Figure 12: DCDC Efficiency from SRC to STO for 1 mA and 10 mA in Low Power Mode

## 12.2. DCDC Conversion Efficiency From SRC to STO in High Power Mode

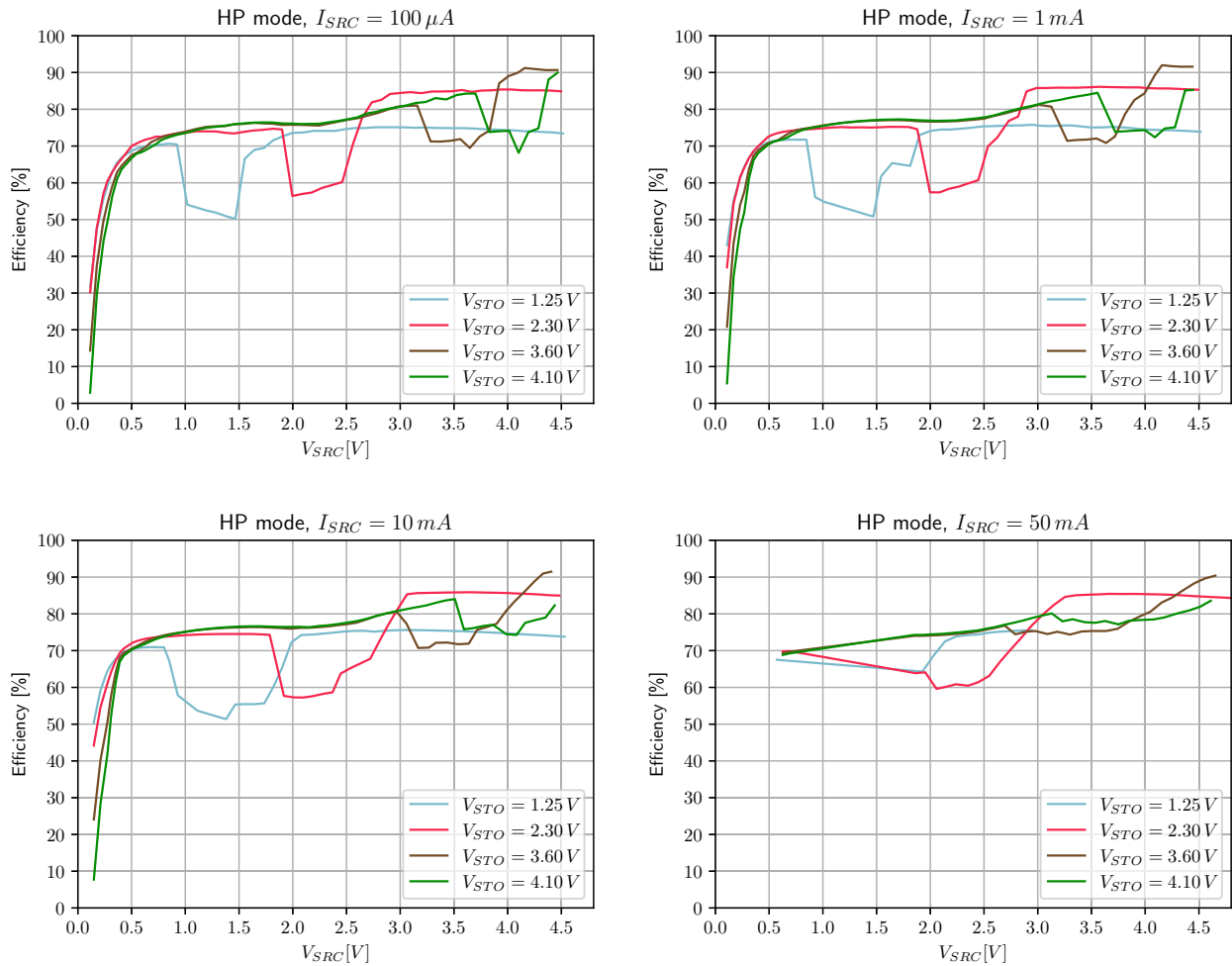


Figure 13: DCDC Efficiency from SRC to STO for 10 mA and 50 mA in High Power Mode

### 12.3. DCDC Conversion Efficiency From STO to LOAD in Low Power Mode

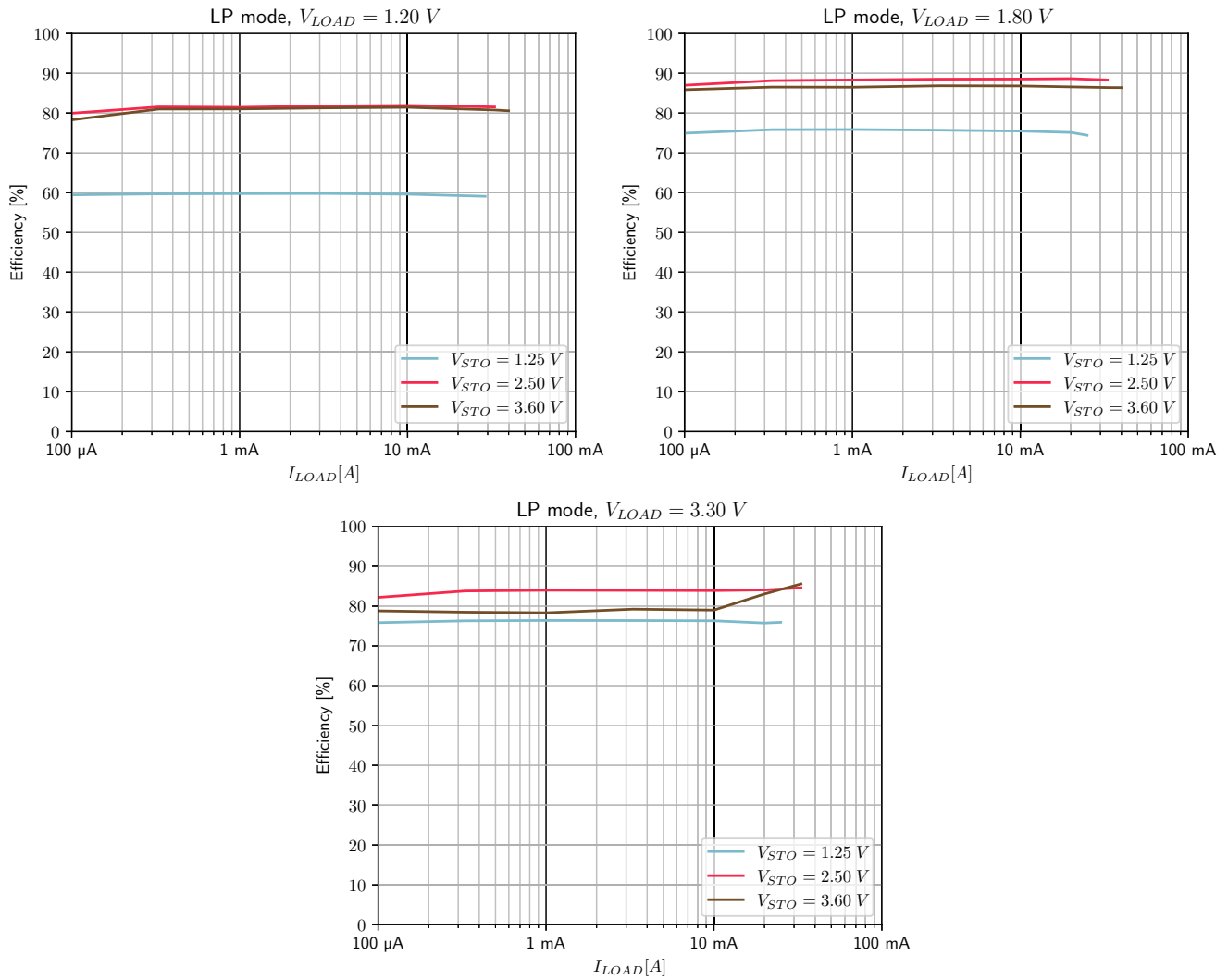


Figure 14: DCDC Efficiency from STO to LOAD in Low Power Mode

## 12.4. DCDC Conversion Efficiency From STO to LOAD in High Power Mode

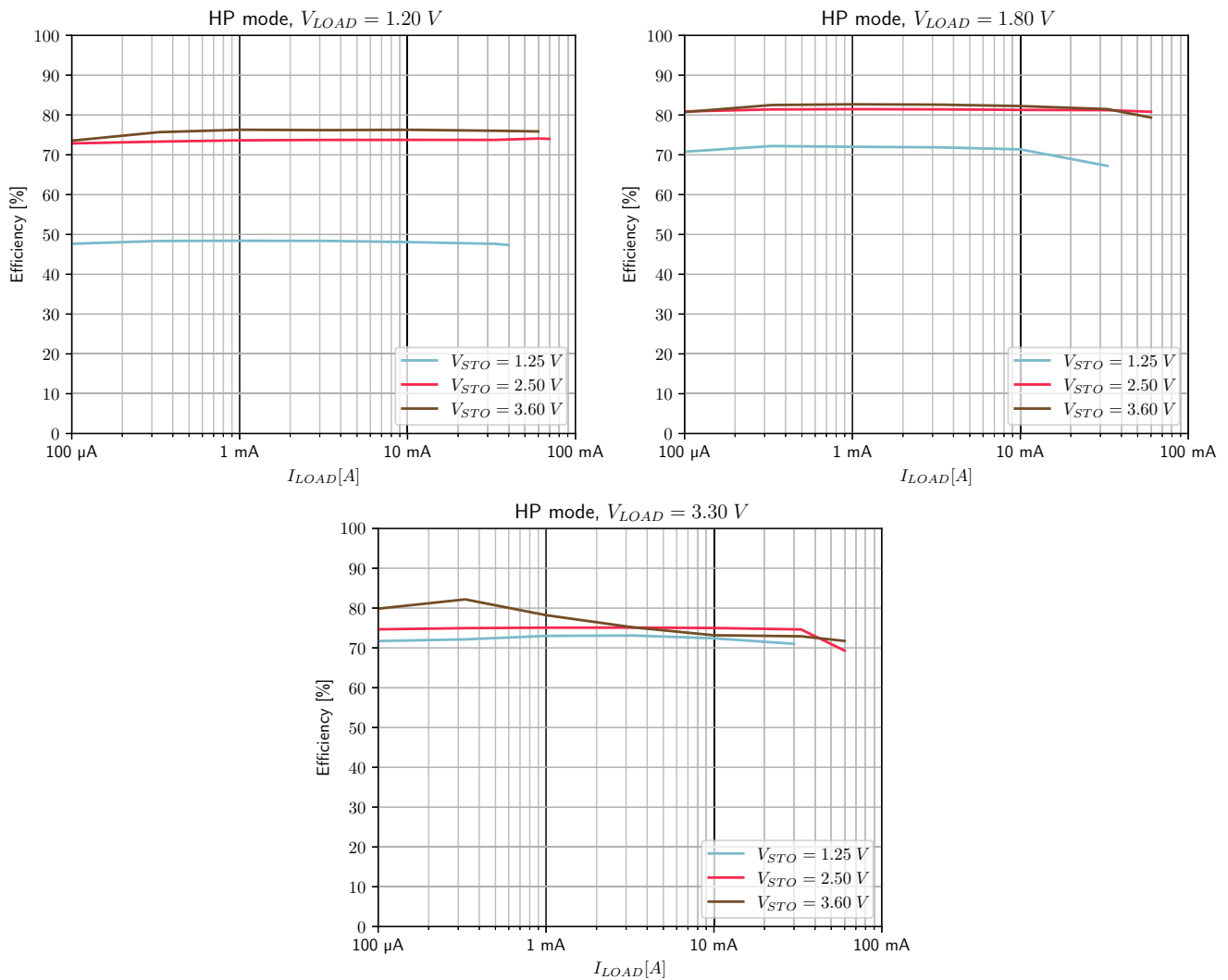


Figure 15: DCDC Efficiency from STO to LOAD in High Power Mode



## 12.5. Quiescent Current

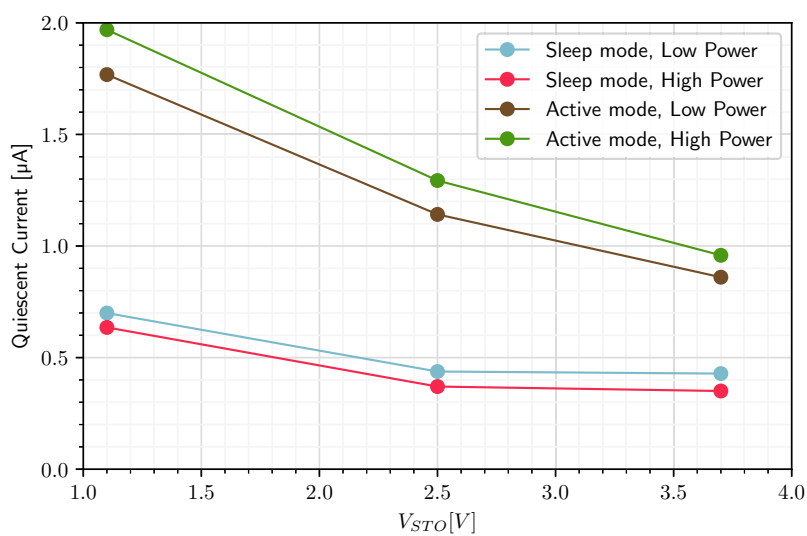


Figure 16: Quiescent Current

## 13. Schematic

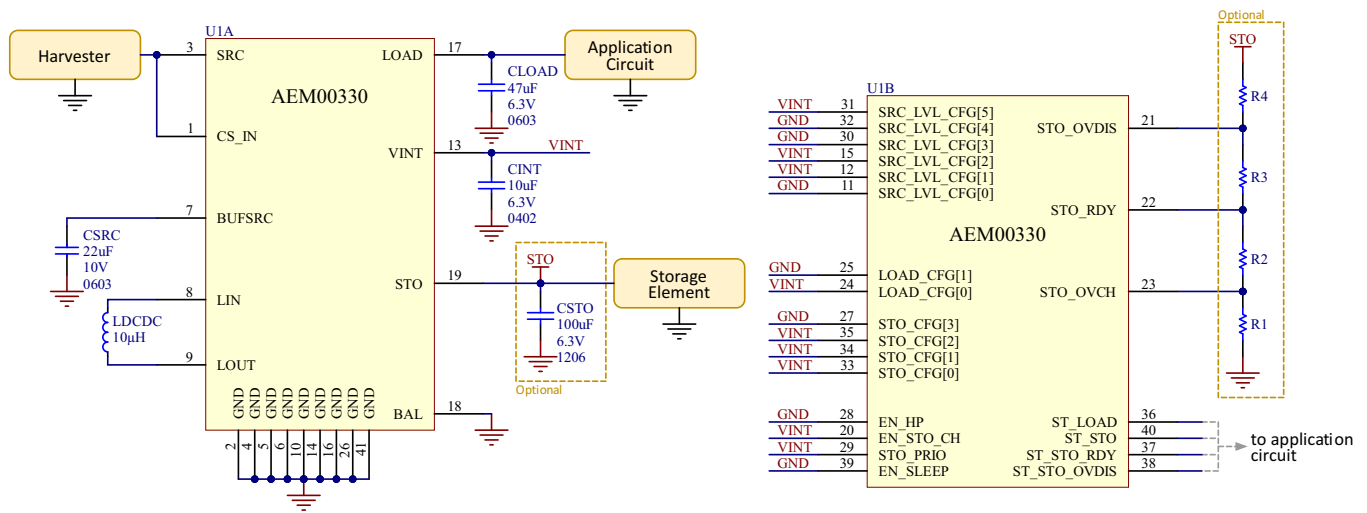


Figure 17: Schematic Example

Designator	Description	Quantity	Manufacturer	Link
U1	AEM00330 - Symbol QFN 40-pin	1	e-peas	order at sales@e-peas.com
L <sub>DCDC</sub>	Power inductor 10 µH - 1.76A	1	Murata	DFE252010F-100M
C <sub>LOAD</sub>	Ceramic Cap 47 µF, 6.3V, 20%, X5R 0603	1	Murata	GRM188R60J476ME15
C <sub>INT</sub>	Ceramic Cap 10 µF, 6.3V, 20%, X5R 0402	1	Murata	GRM155R60J106ME15
C <sub>SRC</sub>	Ceramic Cap 22 µF, 10V, 20%, X5R 0603	1	Murata	GRM188R61A226ME15D
C <sub>STO</sub> (optional)	Ceramic Cap 100 µF, 6.3V, 20%, X5R 1206	1	TDK	C3216X5R1A107M160AC

Table 11: Minimal Bill of Materials

## 14. Layout

### 14.1. Guidelines

Good layout practices are mandatory in order to obtain good stability and best efficiency with the AEM00330. It also allows for minimizing electromagnetic interferences generated by the AEM00330 DCDC converter.

The following list, while not exhaustive, shows the main attention points when routing a PCB with the AEM00330:

- The switching nodes (LIN and LOUT) must be kept as short as possible, with minimal track resistance and minimal track capacitance. Low resistance is obtained by keeping track length as short as possible and track width as large as possible between  $L_{DCDC}$  and the AEM00330 pins. Minimal capacitance is obtained by keeping distance between LIN/LOUT and other signals. We recommend removing the ground plane, the power plane and the bottom layer ground pour under  $L_{DCDC}$  footprint, as well as adding distance between LIN/LOUT and the top ground pour, as shown on Figure 18.
- The DCDC decoupling capacitors ( $C_{SRC}$  -  $C_{LOAD}$  -  $C_{STO}$ ) must be placed as close as possible to the AEM00330, with direct connection and minimum track resistance for the corresponding power nodes (BUFSRC, LOAD and STO).
- The GND return path between the DCDC decoupling capacitors ( $C_{SRC}$  -  $C_{LOAD}$  -  $C_{STO}$ ) and the AEM00330 thermal pad, which is the AEM00330 main GND connection, must be as direct and short as possible. This is preferably done on the top layer when possible, otherwise by internal/bottom plane, using low resistance vias to decrease layer-to-layer connection resistance.
- The external DC power connections (SRC, LOAD and STO) must be connected to the AEM00330 with low resistance tracks.
- Connection between VINT and  $C_{INT}$  must be moderately short for AEM00330 stability, even though this pins does not carry large currents. Same for connection between  $C_{INT}$  to GND.
- The BAL pin connection track must be able to handle at least 40 mA.
- The custom mode setting pins STO\_OVDIS, STO\_RDY and STO\_OVCH are high impedance analog inputs typically connected to a resistive divider with high resistor values, making those three nodes prone to pickup noise. Thus it is recommended to keep those as short as possible and as far as possible to noise sources such as DCDC switching nodes.
- The configuration pins and the status pins have minimal layout restrictions. CS\_IN maximum current is below 1 mA, so its layout restrictions are minimal as well.



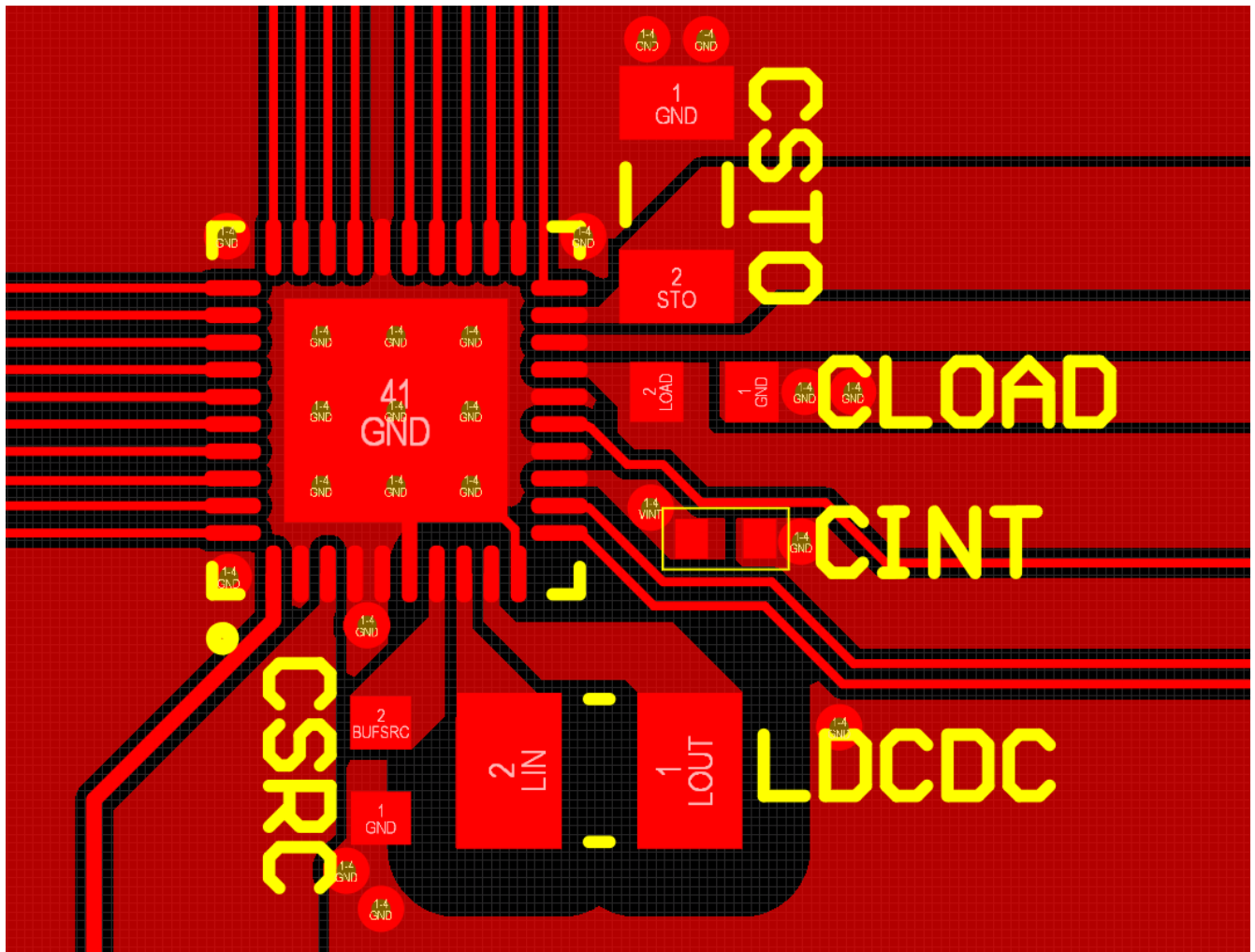
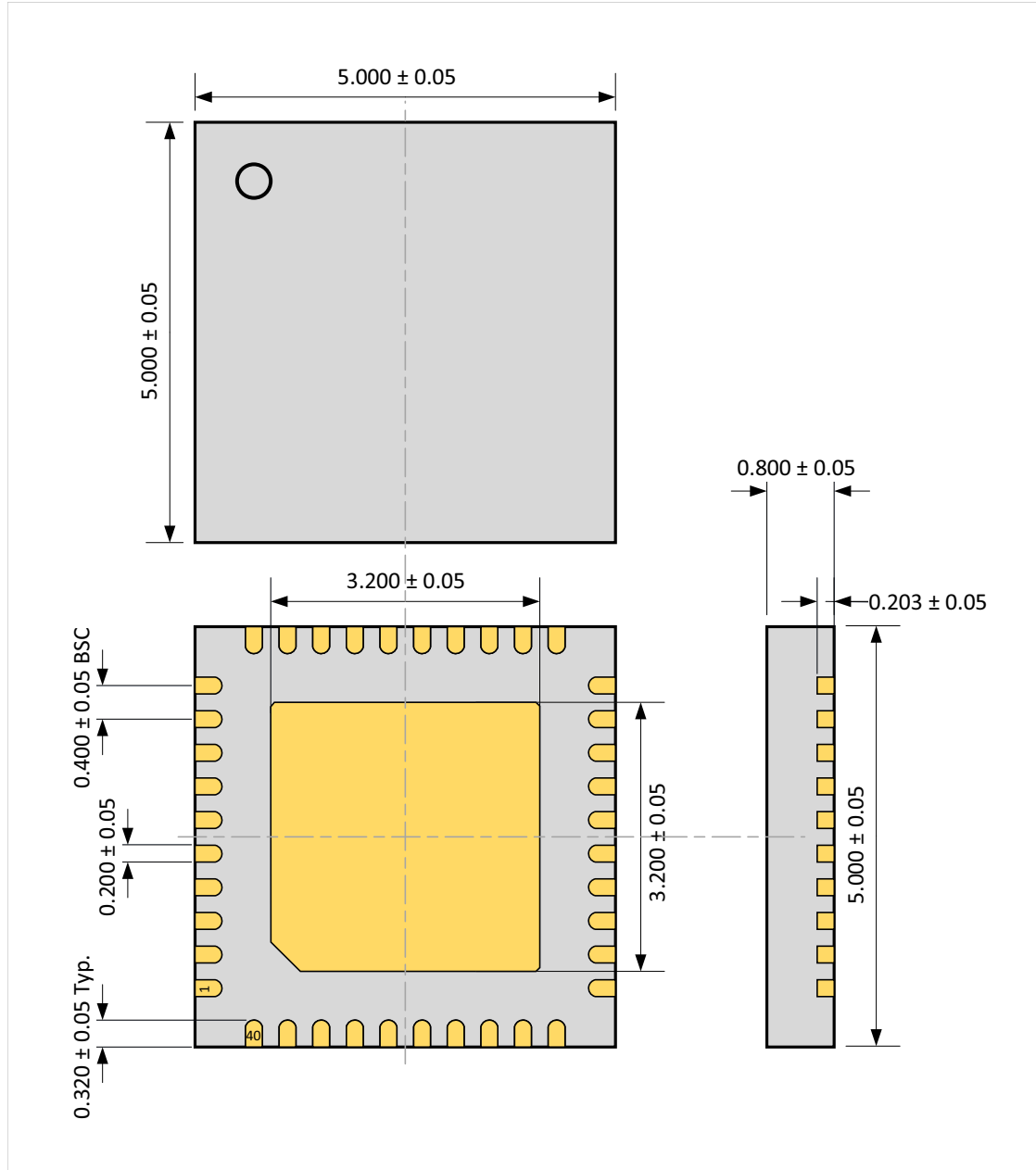


Figure 18: Layout Example for the AEM00330 and its Passive Components

*NOTE: schematic, symbol and footprint for the e-peas component can be ordered by contacting e-peas support team at [support@e-peas.com](mailto:support@e-peas.com)*

## 15. Package Information

### 15.1. Plastic Quad Flatpack No-Lead (QFN 40-pin 5x5mm)



## 15.2. Board Layout

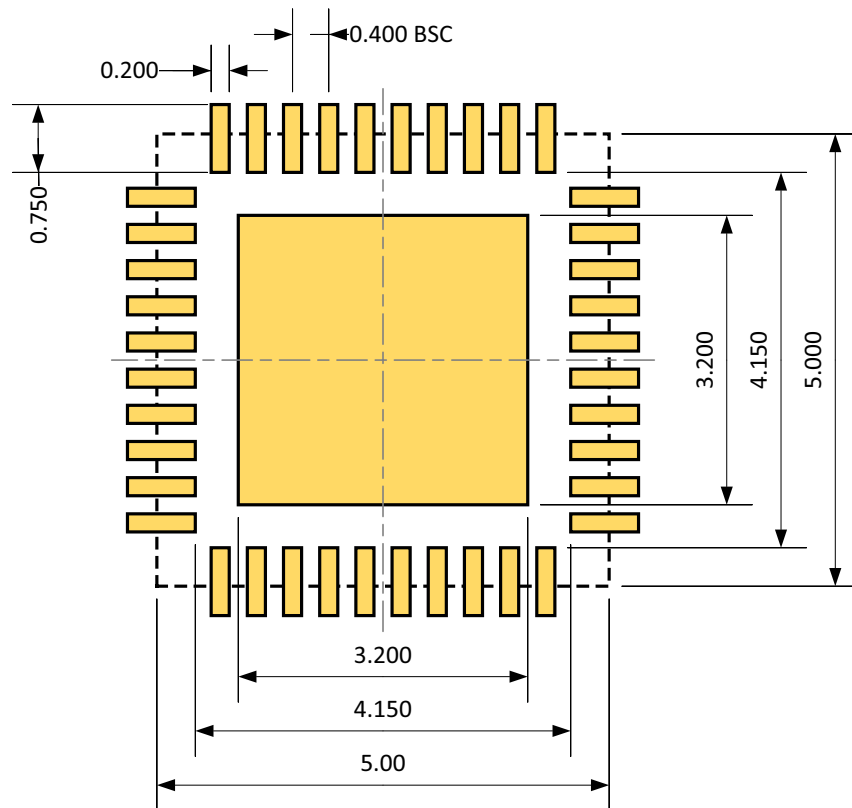


Figure 20: Recommended Board Layout for QFN40 package (All Dimensions in mm)

## 16. Revision History

Revision	Date	Description
0.0	January, 2021	Creation of the document. Preliminary version.
1.0	June, 2021	First version of the document
1.1	August, 2021	Minor modifications
1.2	March, 2023	<ul style="list-style-type: none"> <li>- Various aesthetic improvements.</li> <li>- Explanations about BAL circuit.</li> <li>- Section with precisions about the use of CS_IN.</li> <li>- Removed LOAD_CFG[2] and related configurations.</li> <li>- New "behavior" oscilloscope graphs with improved description.</li> <li>- Moved various states description sections as sub-sections of a global section.</li> <li>- Supply State description: explanation about SRC being set to high impedance when all nodes are fully charged.</li> <li>- Updated "Typical use" of storage element vs STO_CFG[3:0] configuration.</li> <li>- Replaced "asserted/de-asserted" by "HIGH/LOW".</li> <li>- Changed CSRC from 15μF/0402 to 22μF/0603.</li> <li>- Updated "Recommended Operation Conditions" with minimum capacitor values including derating and tolerances.</li> <li>- Removed wrong dimension from package dimensions figure.</li> <li>- Source in application example 1: replaced RF by PV cell.</li> </ul>
1.3	November, 2023	<ul style="list-style-type: none"> <li>- Updated efficiency graphs.</li> <li>- Created section for pinout.</li> <li>- Corrected pin 38 name.</li> <li>- Updated schematics with new symbol.</li> <li>- Digital levels High/Low: replaced 0/1 notation by L/H.</li> <li>- Fixed example circuits errors.</li> <li>- Fixed typos and aesthetic issues.</li> <li>- Added layout guidelines with clearer layout examples.</li> </ul>
1.4	February, 2024	Fixed wrong HIGH level of <b>ST_STO</b> in "Power and Status Pins" table.

Table 12: Revision History

# Mouser Electronics

Authorized Distributor

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